



**Siva Chandra Jangam**  
3DIC Technologist, Apple

SivaChandra Jangam received his Bachelor of Tech. degree in Electrical Engineering from Indian Institute of Technology Kanpur, (IIT Kanpur) India in 2015, and Master of Science, Ph.D. degrees in Electrical Engineering from the University of California, Los Angeles (UCLA) in 2017 and 2020, respectively. He was a part of the Center for Heterogeneous Integration and Performance Scaling (CHIPS) under the guidance of Prof. Subramanian Iyer. His research interests include heterogeneous integration, advanced packaging, and system scaling. His doctoral research was on the development of the Silicon-Interconnect Fabric (Si-IF) technology which is a fine-pitch (10  $\mu\text{m}$ ), high-bandwidth, low latency, and low power heterogeneous integration platform. He pioneered the development of the silicon substrate technology, fine-pitch assembly techniques, and high-bandwidth communication interface. He is currently working as 3D IC Technologist at Apple, Cupertino, CA as part of the Silicon Engineering Group (SEG- Packaging), developing Advanced Packaging solutions.

Siva is co-author of over 20 articles, co-inventor of 2 patents, and the recipient of the Electronics Packaging Society (EPS) Ph.D. fellowship 2019, the Guru Krupa Fellowship 2017. He was also awarded the “Intel Best Student Paper” in the 2017 Electronic Components and Packaging Conference (ECTC), and the “Outstanding student paper award” in the 2018 International Microelectronics Symposium (IMAPS).